Preferred Device

Sensitive Gate Triacs

Silicon Bidirectional Thyristors

Designed for industrial and consumer applications for full wave control of ac loads such as appliance controls, heater controls, motor controls, and other power switching applications.

Features

- Sensitive Gate Allows Triggering by Microcontrollers and other Logic Circuits
- Uniform Gate Trigger Currents in Three Quadrants; Q1, Q2, and Q3
- High Immunity to $dv/dt 25 V/\mu s$ Minimum at $110^{\circ}C$
- High Commutating di/dt 8.0 A/ms Minimum at 110°C
- Maximum Values of I_{GT} , V_{GT} and I_H Specified for Ease of Design
- On-State Current Rating of 8 Amperes RMS at 70°C
- High Surge Current Capability 70 Amperes
- Blocking Voltage to 800 Volts
- Rugged, Economical TO-220AB Package
- Pb–Free Packages are Available*

MAXIMUM RATINGS (T_J = 25° C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage (Note 1) (T _J = -40 to 110°C, Sine Wave, 50 to 60 Hz, Gate Open) MAC8SD MAC8SM MAC8SN	Vdrm, V _{rrm}	400 600 800	V
On-State RMS Current (Full Cycle Sine Wave, 60 Hz, T _C = 70°C)	I _{T(RMS)}	8.0	A
Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz, $T_J = 110^{\circ}$ C)	I _{TSM}	70	A
Circuit Fusing Consideration (t = 8.3 ms)	l ² t	20	A ² sec
Peak Gate Power (Pulse Width \leq 1.0 μ s, T _C = 70°C)	P _{GM}	16	W
Average Gate Power (t = 8.3 ms, $T_C = 70^{\circ}C$)	P _{G(AV)}	0.35	W
Operating Junction Temperature Range	TJ	-40 to +110	°C
Storage Temperature Range	T _{stg}	-40 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

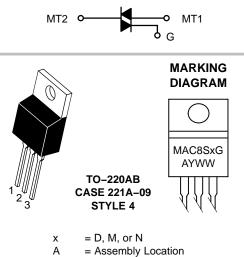
*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



ON Semiconductor®

http://onsemi.com

TRIACS 8 AMPERES RMS 400 thru 800 VOLTS



A = Assembly Locat Y = Year

WW = Work Week G = Pb-Free Package

PIN ASSIGNMENT				
1	Main Terminal 1			
2	Main Terminal 2			
3	Gate			
4	Main Terminal 2			

ORDERING INFORMATION

Device	Package	Shipping
MAC8SD	TO-220AB	50 Units / Rail
MAC8SDG	TO-220AB (Pb-Free)	50 Units / Rail
MAC8SM	TO-220AB	50 Units / Rail
MAC8SMG	TO-220AB (Pb-Free)	50 Units / Rail
MAC8SN	TO-220AB	50 Units / Rail
MAC8SNG	TO-220AB (Pb-Free)	50 Units / Rail

Preferred devices are recommended choices for future use and best overall value.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case Junction-to-Ambient	$\begin{array}{c} R_{\thetaJC} \\ R_{\thetaJA} \end{array}$	2.2 62.5	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	TL	260	°C

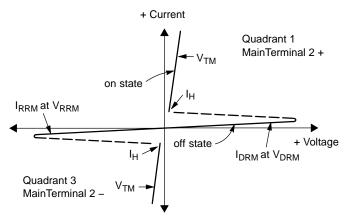
ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted; Electricals apply in both directions)

Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	HARACTERISTICS Repetitive Blocking Current = Rated V _{DRM} , V _{RRM} ; Gate Open) T _J = 25°C T _J = 110°C IDRM, IRRM - - 0.01 2.0 mA ARACTERISTICS On-State Voltage (Note) (I _{TM} = ± 11A) V T - - 0.01 2.0 mA On-State Voltage (Note) (I _{TM} = ± 11A) V T - 1.85 V On-State Voltage (Note) (I _{TM} = ± 11A) V T - 1.85 V On-State Voltage (Continuous dc) (V _D = 12 V, R _L = 100 Ω) V T - 2.0 5.0 S g Current (V _D = 12V, Gate Open, Initiating Current = ± 150mA) IL - - 1.0 MA g Current (V _D = 24V, I _G = 5mA) IL - 5.0 15 - 1.0 2.0 5.					
Peak Repetitive Blocking Current (V _D = Rated V _{DRM} , V _{RRM} ; Gate Open)	•		- -			mA
ON CHARACTERISTICS						
Peak On-State Voltage (Note) ($I_{TM} = \pm 11A$)		V _{TM}	_	-	1.85	V
Gate Trigger Current (Continuous dc) ($V_D = 12 V$, $R_L = 100 \Omega$) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-)		I _{GT}	- - -	3.0	5.0	mA
Holding Current (V _D = 12V, Gate Open, Initiating Current = \pm 150mA)		Ι _Η	_	3.0	10	mA
Latching Current ($V_D = 24V$, $I_G = 5mA$) MT2(+), G(+) MT2(-), G(-) MT2(+), G(-)		ι	- - -	10	20	mA
Gate Trigger Voltage (Continuous dc) ($V_D = 12 V$, $R_L = 100\Omega$) MT2(+), G(+) MT2(+), G(-) MT2(-), G(-)		V _{GT}	0.45	0.60	1.5	V
DYNAMIC CHARACTERISTICS					1	_1
Rate of Change of Commutating Current $V_D = 400 \text{ V}, \text{ I}_{TM} = 3.5 \text{ A}, \text{ Commutating dv/dt} = 10 \text{ V} \mu/\text{sec},$ Gate Open, $T_J = 110^{\circ}\text{C}, \text{ f} = 500 \text{ Hz}, \text{ Snubber: } C_S = 0.01 \mu\text{F},$ $R_S = 15 \Omega$, See Figure 16.)		di/dt _(c)	8.0	10	_	A/ms
Critical Rate of Rise of Off-State Voltage $(V_D = Rate V_{DRM}, Exponential Waveform, R_{GK} = 510 \Omega, T_J = 110^{\circ}C)$		dv/dt	25	75	-	V/µs

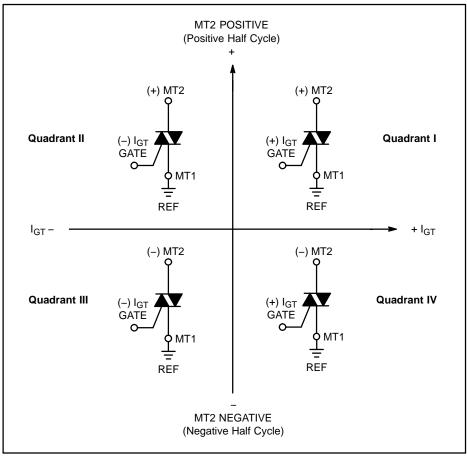
2. Indicates Pulse Test: Pulse Width \leq 2.0 ms, Duty Cycle \leq 2%.

Voltage Current Characteristic of Triacs (Bidirectional Device)

Symbol	Parameter
V _{DRM}	Peak Repetitive Forward Off State Voltage
I _{DRM}	Peak Forward Blocking Current
V _{RRM}	Peak Repetitive Reverse Off State Voltage
I _{RRM}	Peak Reverse Blocking Current
V _{TM}	Maximum On State Voltage
I _H	Holding Current

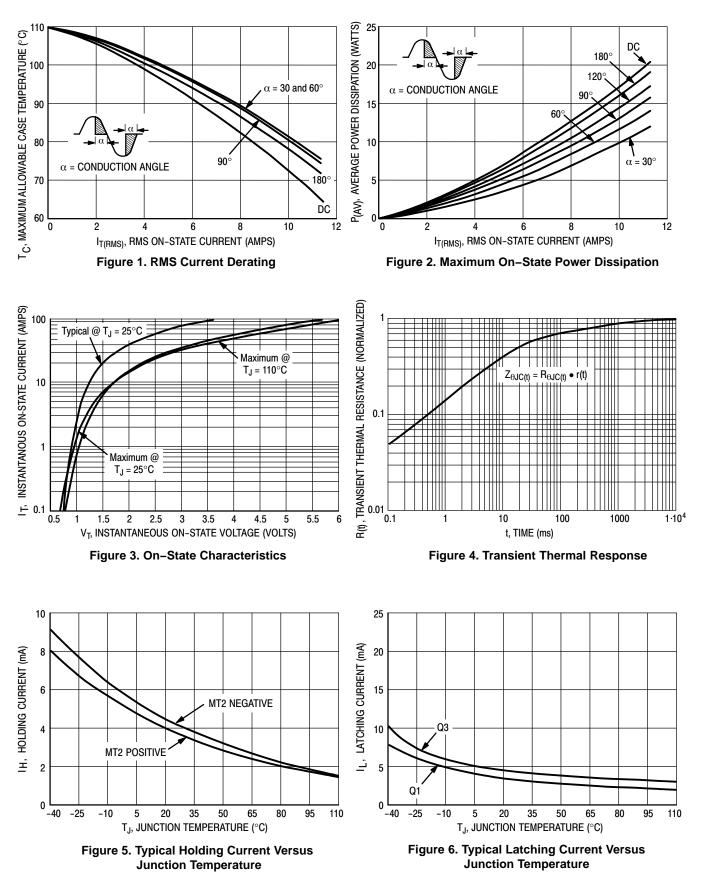


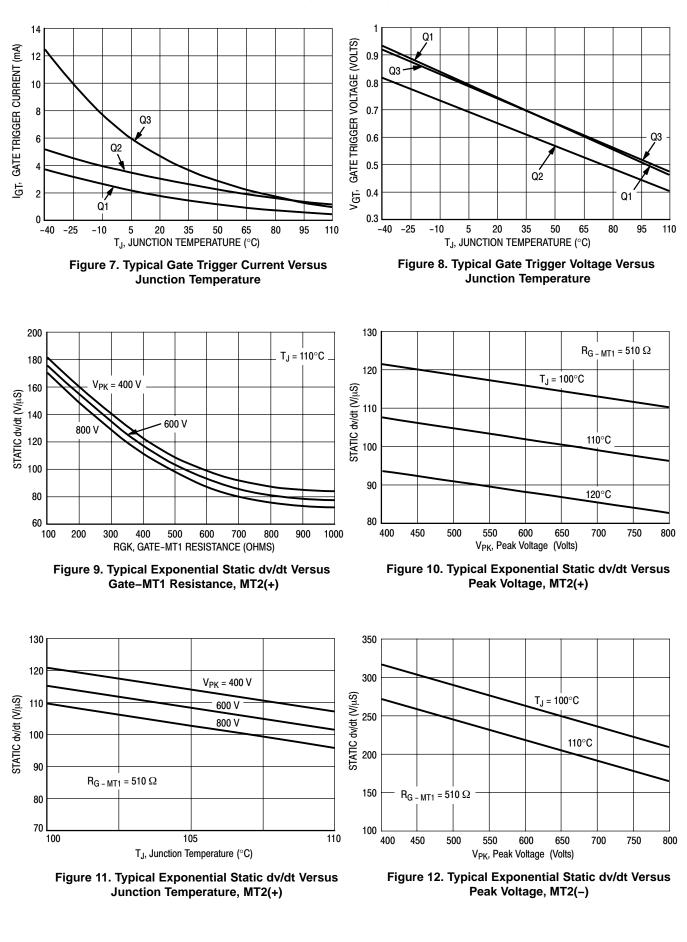
Quadrant Definitions for a Triac

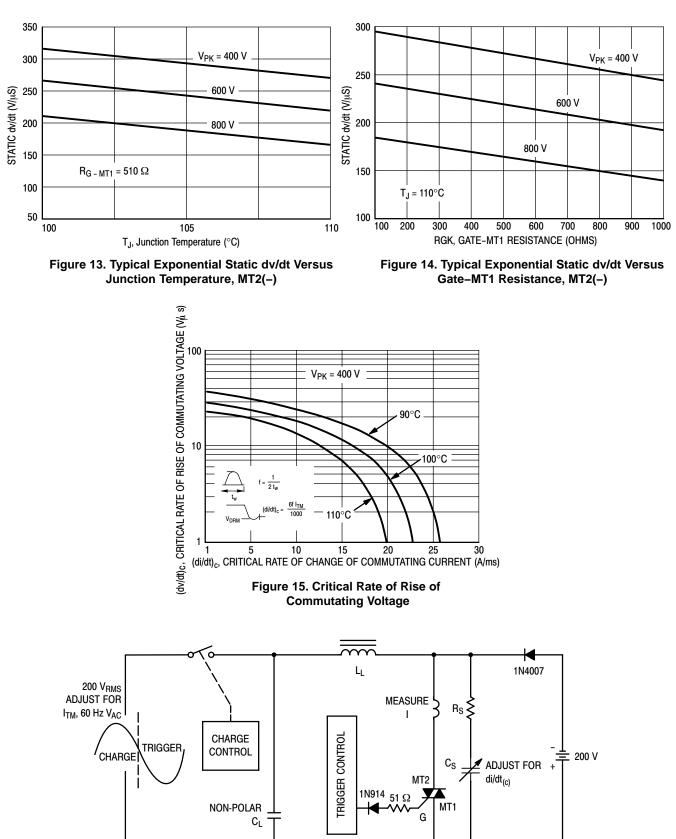


All polarities are referenced to MT1.

With in-phase signals (using standard AC lines) quadrants I and III are used.





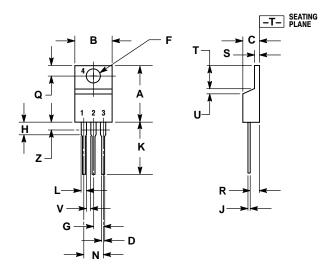


Note: Component values are for verification of rated (di/dt)_c. See AN1048 for additional information.



PACKAGE DIMENSIONS

TO-220AB CASE 221A-09 ISSUE AA



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 DIMENSION Z DEFINES A ZONE WHERE ALL.

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ALLO\	VED.			

	INCHES		MILLIN	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
н	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
Κ	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
Ν	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
۷	0.045		1.15	
Ζ		0.080		2.04
		AIN TERM		

3. GATE

4

MAIN TERMINAL 2

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